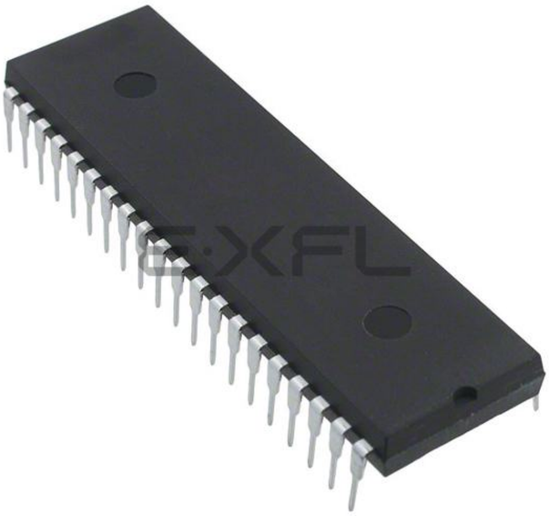
Microchip Technology - PIC16F1937-E/P Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1937-e-p

5.4 Two-Speed Clock Start-up Mode

Two-Speed Start-up mode provides additional power savings by minimizing the latency between external oscillator start-up and code execution. In applications that make heavy use of the Sleep mode, Two-Speed Start-up will remove the external oscillator start-up time from the time spent awake and can reduce the overall power consumption of the device. This mode allows the application to wake-up from Sleep, perform a few instructions using the INTOSC internal oscillator block as the clock source and go back to Sleep without waiting for the external oscillator to become stable.

Two-Speed Start-up provides benefits when the oscillator module is configured for LP, XT or HS modes. The Oscillator Start-up Timer (OST) is enabled for these modes and must count 1024 oscillations before the oscillator can be used as the system clock source.

If the oscillator module is configured for any mode other than LP, XT or HS mode, then Two-Speed Start-up is disabled. This is because the external clock oscillator does not require any stabilization time after POR or an exit from Sleep.

If the OST count reaches 1024 before the device enters Sleep mode, the OSTS bit of the OSCSTAT register is set and program execution switches to the external oscillator. However, the system may never operate from the external oscillator if the time spent awake is very short.

Note: Executing a `SLEEP` instruction will abort the oscillator start-up time and will cause the OSTS bit of the OSCSTAT register to remain clear.

5.4.1 TWO-SPEED START-UP MODE CONFIGURATION

Two-Speed Start-up mode is configured by the following settings:

- IESO (of the Configuration Word 1) = `1`; Internal/External Switchover bit (Two-Speed Start-up mode enabled).
- SCS (of the OSCCON register) = `00`.
- FOSC<2:0> bits in the Configuration Word 1 configured for LP, XT or HS mode.

Two-Speed Start-up mode is entered after:

- Power-on Reset (POR) and, if enabled, after Power-up Timer (PWRT) has expired, or
- Wake-up from Sleep.

TABLE 5-1: OSCILLATOR SWITCHING DELAYS

Switch From	Switch To	Frequency	Oscillator Delay
Sleep/POR	LFINTOSC(1) MFINTOSC(1) HFINTOSC(1)	31 kHz 31.25 kHz-500 kHz 31.25 kHz-16 MHz	Oscillator Warm-up Delay (T_{WARM})
Sleep/POR	EC, RC(1)	DC – 32 MHz	2 cycles
LFINTOSC	EC, RC(1)	DC – 32 MHz	1 cycle of each
Sleep/POR	Timer1 Oscillator LP, XT, HS(1)	32 kHz-20 MHz	1024 Clock Cycles (OST)
Any clock source	MFINTOSC(1) HFINTOSC(1)	31.25 kHz-500 kHz 31.25 kHz-16 MHz	2 μs (approx.)
Any clock source	LFINTOSC(1)	31 kHz	1 cycle of each
Any clock source	Timer1 Oscillator	32 kHz	1024 Clock Cycles (OST)
PLL inactive	PLL active	16-32 MHz	2 ms (approx.)

Note 1: PLL inactive.

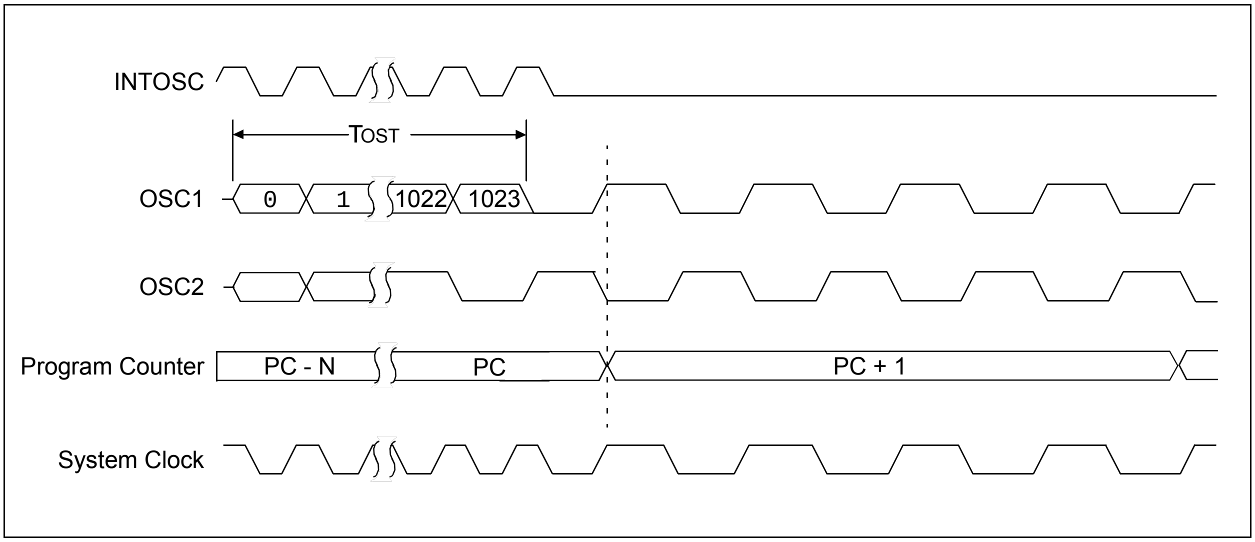
5.4.2 TWO-SPEED START-UP SEQUENCE

1. Wake-up from Power-on Reset or Sleep.
2. Instructions begin execution by the internal oscillator at the frequency set in the IRCF<3:0> bits of the OSCCON register.
3. OST enabled to count 1024 clock cycles.
4. OST timed out, wait for falling edge of the internal oscillator.
5. OSTS is set.
6. System clock held low until the next falling edge of new clock (LP, XT or HS mode).
7. System clock is switched to external clock source.

5.4.3 CHECKING TWO-SPEED CLOCK STATUS

Checking the state of the OSTS bit of the OSCSTAT register will confirm if the microcontroller is running from the external clock source, as defined by the FOSC<2:0> bits in the Configuration Word 1, or the internal oscillator.

FIGURE 5-8: TWO-SPEED START-UP



REGISTER 12-5: ANSELA: PORTA ANALOG SELECT REGISTER

U-0	U-0	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
—	—	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘`0`’

bit 5-0 **ANSA<5:0>**: Analog Select between Analog or Digital Function on pins RA<5:0>, respectively
`0` = Digital I/O. Pin is assigned to port or digital special function.
`1` = Analog input. Pin is assigned as analog input**(1)**. Digital input buffer disabled.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

TABLE 12-6: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ADCON0	—	CHS<4:0>					GO/$\overline{\text{DONE}}$	ADON	163
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	139
APFCON	—	CCP3SEL	T1GSEL	P2BSEL	SRNQSEL	C2OUTSEL	SSSEL	CCP2SEL	131
CCPxCON	PxM<1:0>		DCxB<1:0>		CCPxM<3:0>				234
CPSCON0	CPSON	—	—	—	CPSRNG<1:0>		CPSOUT	T0XCS	323
CPSCON1	—	—	—	—	CPSCH<3:>				324
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	98
IOCBP	IOCBP7	IOCBP6	IOCBP5	IOCBP4	IOCBP3	IOCBP2	IOCBP1	IOCBP0	152
IOCBN	IOCBN7	IOCBN6	IOCBN5	IOCBN4	IOCBN3	IOCBN2	IOCBN1	IOCBN0	152
IOCBF	IOCBF7	IOCBF6	IOCBF5	IOCBF4	IOCBF3	IOCBF2	IOCBF1	IOCBF0	152
LATB	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	138
LCDCON	LCDEN	SLPEN	WERR	—	CS<1:0>		LMUX<1:0>		329
LCDSE0	SE7	SE6	SE5	SE4	SE3	SE2	SE1	SE0	333
LCDSE1	SE15	SE14	SE13	SE12	SE11	SE10	SE9	SE8	333
OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			193
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	138
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/$\overline{\text{DONE}}$	T1GVAL	T1GSS<1:0>		204
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	138
WPUB	WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0	139

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTB.

FIGURE 21-6: TIMER1 GATE SINGLE-PULSE AND TOGGLE COMBINED MODE

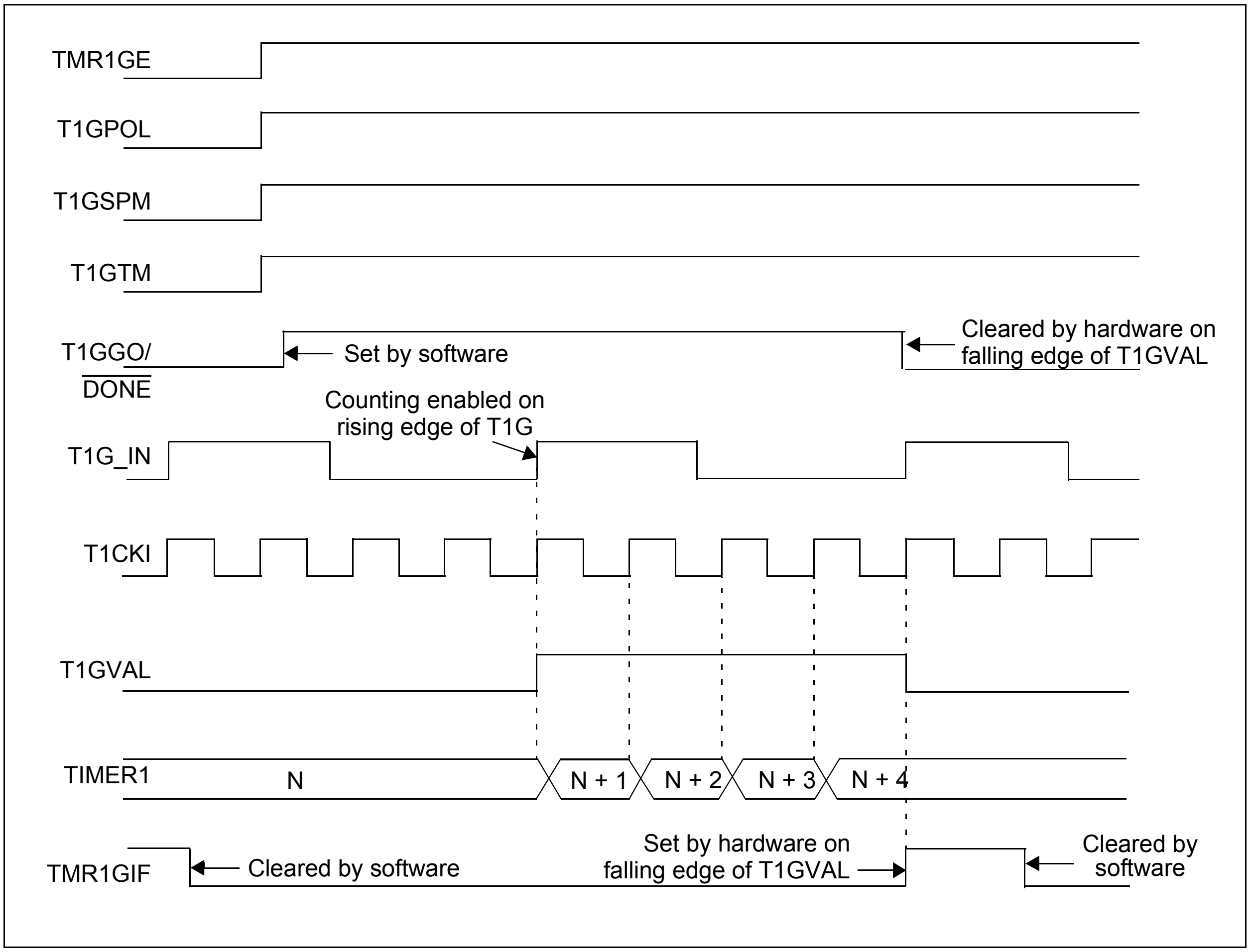
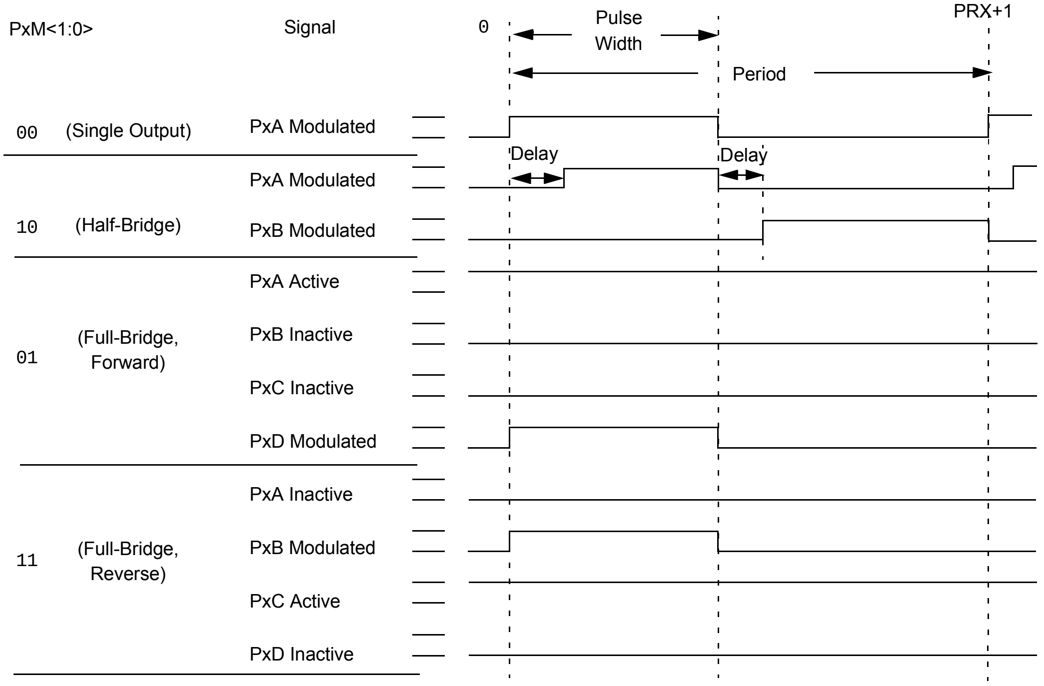


TABLE 23-9: EXAMPLE PIN ASSIGNMENTS FOR VARIOUS PWM ENHANCED MODES

ECCP Mode	PxM<1:0>	CCPx/PxA	PxB	PxC	PxD
Single	`00`	Yes[(1)]	Yes[(1)]	Yes[(1)]	Yes[(1)]
Half-Bridge	`10`	Yes	Yes	No	No
Full-Bridge, Forward	`01`	Yes	Yes	Yes	Yes
Full-Bridge, Reverse	`11`	Yes	Yes	Yes	Yes

Note 1: PWM Steering enables outputs in Single mode.

FIGURE 23-6: EXAMPLE PWM (ENHANCED MODE) OUTPUT RELATIONSHIPS (ACTIVE-HIGH STATE)



Relationships:
- Period = 4 * TOSC * (PRx + 1) * (TMRx Prescale Value)
- Pulse Width = TOSC * (CCPRxL<7:0>:CCPxCON<5:4>) * (TMRx Prescale Value)
- Delay = 4 * TOSC * (PWMxCON<6:0>)

24.6.5 I^{2}C MASTER MODE REPEATED START CONDITION TIMING

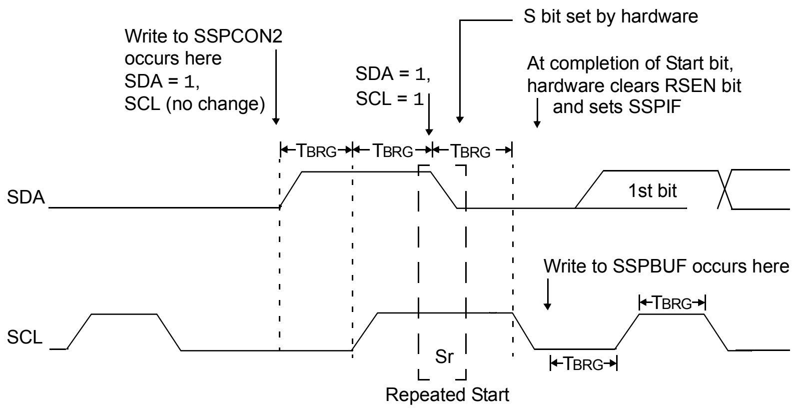
A Repeated Start condition occurs when the RSEN bit of the SSPCON2 register is programmed high and the Master state machine is no longer active. When the RSEN bit is set, the SCL pin is asserted low. When the SCL pin is sampled low, the Baud Rate Generator is loaded and begins counting. The SDA pin is released (brought high) for one Baud Rate Generator count (TBRG). When the Baud Rate Generator times out, if SDA is sampled high, the SCL pin will be deasserted (brought high). When SCL is sampled high, the Baud Rate Generator is reloaded and begins counting. SDA and SCL must be sampled high for one TBRG. This action is then followed by assertion of the SDA pin (SDA = 0) for one TBRG while SCL is high. SCL is asserted low. Following this, the RSEN bit of the SSPCON2 register will be automatically cleared and the Baud Rate Generator will not be reloaded, leaving the SDA pin held low. As soon as a Start condition is detected on the SDA and SCL pins, the S bit of the SSPSTAT register will be set. The SSPIF bit will not be set until the Baud Rate Generator has timed out.

Note 1: If RSEN is programmed while any other event is in progress, it will not take effect.

2: A bus collision during the Repeated Start condition occurs if:

- SDA is sampled low when SCL goes from low-to-high.
- SCL goes low before SDA is asserted low. This may indicate that another master is attempting to transmit a data '1'.

FIGURE 24-27: REPEAT START CONDITION WAVEFORM



27.0 LIQUID CRYSTAL DISPLAY (LCD) DRIVER MODULE

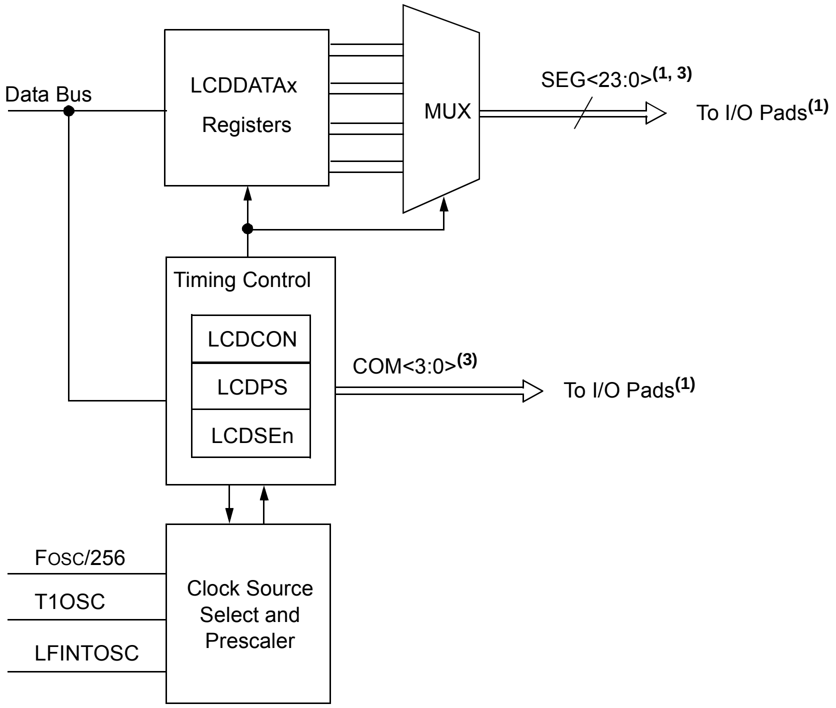
The Liquid Crystal Display (LCD) Driver module generates the timing control to drive a static or multiplexed LCD panel. In the PIC16(L)F1934/6/7 device, the module drives the panels of up to four commons and up to 24 segments. The LCD module also provides control of the LCD pixel data.

The LCD Driver module supports:

- Direct driving of LCD panel
- Three LCD clock sources with selectable prescaler
- Up to four common pins:
  - Static (1 common)
  - 1/2 multiplex (2 commons)
  - 1/3 multiplex (3 commons)
  - 1/4 multiplex (4 commons)
- Segment pins up to:
  - 16 (PIC16(L)F1936)
  - 24 (PIC16(L)F1934/7)
- Static, 1/2 or 1/3 LCD Bias

Note: COM3 and SEG15 share the same physical pin on the PIC16(L)F1936, therefore SEG15 is not available when using 1/4 multiplex displays.

FIGURE 27-1: LCD DRIVER MODULE BLOCK DIAGRAM



Note 1: These are not directly connected to the I/O pads, but may be tri-stated, depending on the configuration of the LCD module.

2: SEG<23:0> on PIC16F1934/1937, SEG<15:0> on PIC16(L)F1936.

3: COM3 and SEG15 share the same physical pin on the PIC16(L)F1936, therefore SEG15 is not available when using 1/4 multiplex displays.

28.0 IN-CIRCUIT SERIAL PROGRAMMING™ (ICSP™)

ICSP™ programming allows customers to manufacture circuit boards with unprogrammed devices. Programming can be done after the assembly process allowing the device to be programmed with the most recent firmware or a custom firmware. Five pins are needed for ICSP™ programming:

- ICSPCLK
- ICSPDAT
- $\overline{\text{MCLR}}$/VPP
- VDD
- VSS

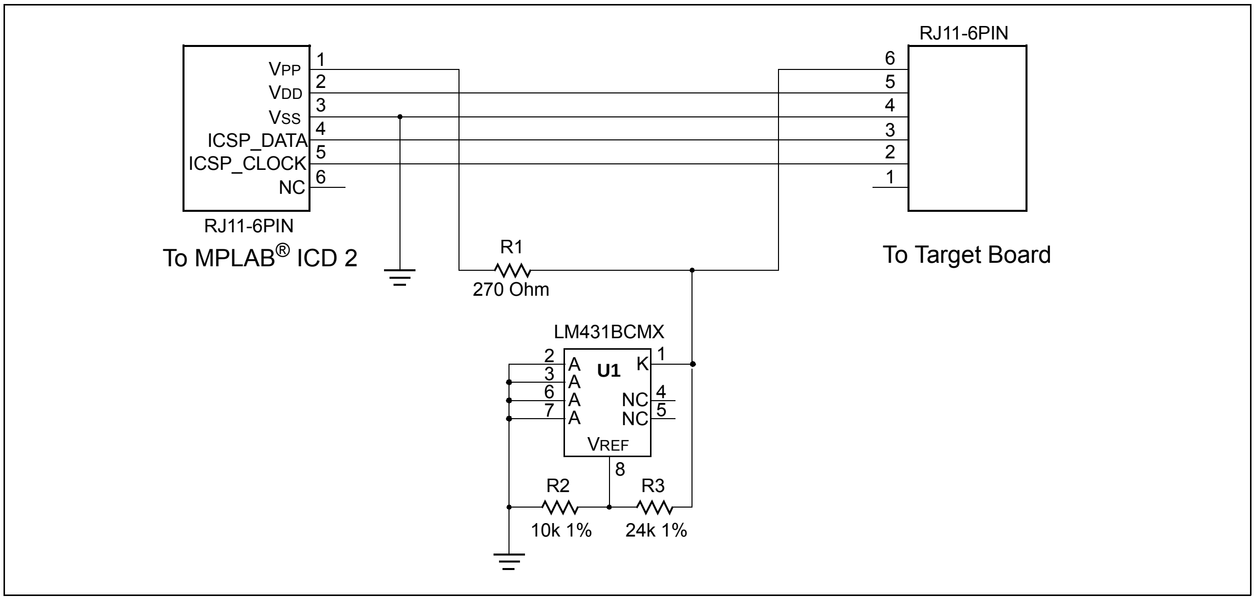
In Program/Verify mode the Program Memory, User IDs and the Configuration Words are programmed through serial communications. The ICSPDAT pin is a bidirectional I/O used for transferring the serial data and the ICSPCLK pin is the clock input. For more information on ICSP™ refer to the "*PIC16193X/PIC16LF193X Memory Programming Specification*" (DS41360).

28.1 High-Voltage Programming Entry Mode

The device is placed into High-Voltage Programming Entry mode by holding the ICSPCLK and ICSPDAT pins low then raising the voltage on $\overline{\text{MCLR}}$/VPP to VIHH.

Some programmers produce VPP greater than VIHH (9.0V), an external circuit is required to limit the VPP voltage. See Figure 28-1 for example circuit.

FIGURE 28-1: VPP LIMITER EXAMPLE CIRCUIT



Note: The MPLAB® ICD 2 produces a VPP voltage greater than the maximum VPP specification of the PIC16(L)F1934/6/7.

29.2 Instruction Descriptions

ADDFSR	**Add Literal to FSRn**
Syntax:	[*label*] ADDFSR FSRn, k
Operands:	$-32 \leq k \leq 31$ $n \in [0, 1]$
Operation:	$FSR(n) + k \rightarrow FSR(n)$
Status Affected:	None
Description:	The signed 6-bit literal ‘k’ is added to the contents of the FSRnH:FSRnL register pair. FSRn is limited to the range 0000h - FFFFh. Moving beyond these bounds will cause the FSR to wrap around.

ADDLW	**Add literal and W**
Syntax:	[*label*] ADDLW k
Operands:	$0 \leq k \leq 255$
Operation:	$(W) + k \rightarrow (W)$
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the eight-bit literal ‘k’ and the result is placed in the W register.

ADDWF	**Add W and f**
Syntax:	[*label*] ADDWF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	$(W) + (f) \rightarrow$ (destination)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register ‘f’. If ‘d’ is ‘`0`’, the result is stored in the W register. If ‘d’ is ‘`1`’, the result is stored back in register ‘f’.

ADDWFC	**ADD W and CARRY bit to f**
Syntax:	[*label*] ADDWFC f {,d}
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	$(W) + (f) + (C) \rightarrow$ dest
Status Affected:	C, DC, Z
Description:	Add W, the Carry flag and data memory location ‘f’. If ‘d’ is ‘`0`’, the result is placed in W. If ‘d’ is ‘`1`’, the result is placed in data memory location ‘f’.

ANDLW	**AND literal with W**
Syntax:	[*label*] ANDLW k
Operands:	$0 \leq k \leq 255$
Operation:	(W) .AND. (k) $\rightarrow$ (W)
Status Affected:	Z
Description:	The contents of W register are AND’ed with the eight-bit literal ‘k’. The result is placed in the W register.

ANDWF	**AND W with f**
Syntax:	[*label*] ANDWF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(W) .AND. (f) $\rightarrow$ (destination)
Status Affected:	Z
Description:	AND the W register with register ‘f’. If ‘d’ is ‘`0`’, the result is stored in the W register. If ‘d’ is ‘`1`’, the result is stored back in register ‘f’.

ASRF	**Arithmetic Right Shift**
Syntax:	[*label*] ASRF f {,d}
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	$(f<7>) \rightarrow dest<7>$ $(f<7:1>) \rightarrow dest<6:0>$, $(f<0>) \rightarrow C$,
Status Affected:	C, Z
Description:	The contents of register ‘f’ are shifted one bit to the right through the Carry flag. The MSb remains unchanged. If ‘d’ is ‘`0`’, the result is placed in W. If ‘d’ is ‘`1`’, the result is stored back in register ‘f’.

RETFIE Return from Interrupt

Syntax:	[*label*] RETFIE
Operands:	None
Operation:	TOS → PC, 1 → GIE
Status Affected:	None
Description:	Return from Interrupt. Stack is POPed and Top-of-Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two-cycle instruction.
Words:	1
Cycles:	2

Example:

```
RETFIE
```

After Interrupt
PC = TOS
GIE = `1`

RETLW Return with literal in W

Syntax:	[*label*] RETLW k
Operands:	$0 \leq k \leq 255$
Operation:	k → (W); TOS → PC
Status Affected:	None
Description:	The W register is loaded with the eight bit literal ‘k’. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.
Words:	1
Cycles:	2

Example:

```
          CALL TABLE;W contains table
              ;offset value
          •   ;W now has table value
TABLE     •
          •
          ADDWF PC  ;W = offset
          RETLW k1  ;Begin table
          RETLW k2  ;
          •
          •
          •
          RETLW kn  ; End of table
```

Before Instruction
W = 0x07
After Instruction
W = value of k8

RETURN Return from Subroutine

Syntax:	[*label*] RETURN
Operands:	None
Operation:	TOS → PC
Status Affected:	None
Description:	Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a two-cycle instruction.

RLF Rotate Left f through Carry

Syntax:	[*label*] RLF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	See description below
Status Affected:	C
Description:	The contents of register ‘f’ are rotated one bit to the left through the Carry flag. If ‘d’ is ‘`0`’, the result is placed in the W register. If ‘d’ is ‘`1`’, the result is stored back in register ‘f’.

Words:	1
Cycles:	1

Example:

```
RLF     REG1,0
```

Before Instruction
```
REG1   =  1110 0110
C      =  0
```
After Instruction
```
REG1   =  1110 0110
W      =  1100 1100
C      =  1
```

30.2 DC Characteristics: PIC16(L)F1934/6/7-I/E (Industrial, Extended) (Continued)

PIC16LF1934/36/37	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended
PIC16F1934/36/37	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	**Device Characteristics**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**	
						VDD	**Note**
D017	**Supply Current (IDD)(1, 2)**						
		—	110	180	µA	1.8	FOSC = 500 kHz MFINTOSC mode
		—	140	250	µA	3.0	
D017		—	150	250	µA	1.8	FOSC = 500 kHz MFINTOSC mode **(Note 5)**
		—	210	330	µA	3.0	
		—	270	430	µA	5.0	
D018		—	1.0	1.4	mA	1.8	FOSC = 8 MHz HFINTOSC mode
		—	1.8	2.3	mA	3.0	
D018		—	1.0	1.5	mA	1.8	FOSC = 8 MHz HFINTOSC mode **(Note 5)**
		—	1.8	2.3	mA	3.0	
		—	2.0	2.8	mA	5.0	
D019		—	1.5	2.2	mA	1.8	FOSC = 16 MHz HFINTOSC mode
		—	2.8	3.7	mA	3.0	
D019		—	1.7	2.3	mA	1.8	FOSC = 16 MHz HFINTOSC mode **(Note 5)**
		—	2.9	3.9	mA	3.0	
		—	3.1	4.1	mA	5.0	
D020		—	4.8	6.2	mA	3.0	FOSC = 32 MHz HFINTOSC mode
		—	5.0	7.5	mA	3.6	
D020		—	4.8	6.5	mA	3.0	FOSC = 32 MHz HFINTOSC mode
		—	5.0	7.5	mA	5.0	
D021		—	410	550	µA	1.8	FOSC = 4 MHz EXTRC mode **(Note 3)**
		—	710	990	µA	3.0	
D021		—	430	700	µA	1.8	FOSC = 4 MHz EXTRC mode **(Note 3, Note 5)**
		—	730	1100	µA	3.0	
		—	860	1400	µA	5.0	
D022		—	5.0	6.2	mA	3.0	FOSC = 32 MHz HS Oscillator mode **(Note 6)**
		—	6.0	7.5	mA	3.6	
D022		—	5.0	6.5	mA	3.0	FOSC = 32 MHz HS Oscillator mode **(Note 5, Note 6)**
		—	5.2	7.5	mA	5.0	

Note 1: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; $\overline{\text{MCLR}}$ = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

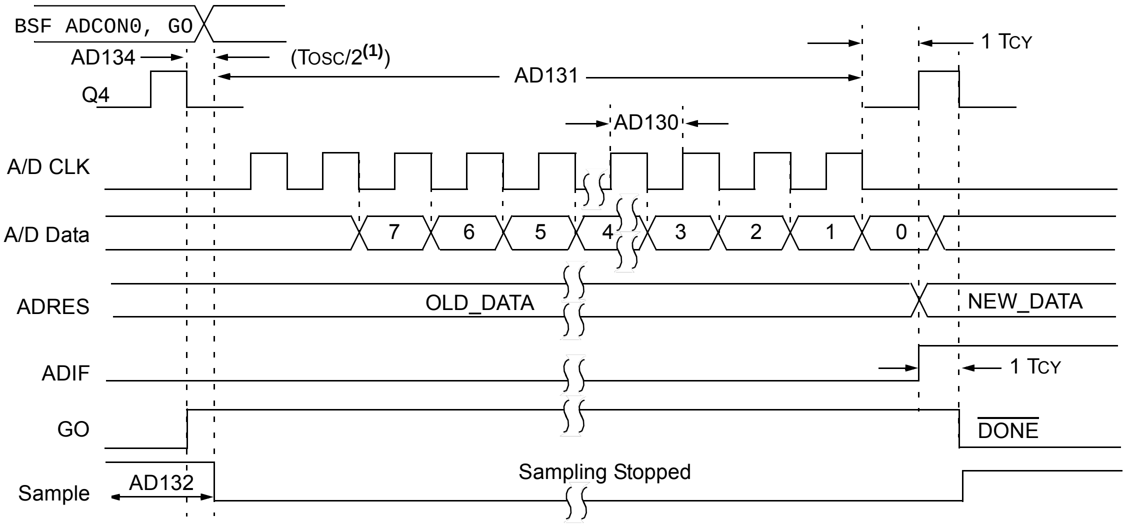
3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula IR = VDD/2REXT (mA) with REXT in kΩ.

4: FVR and BOR are disabled.

5: 0.1 µF capacitor on VCAP (RA0).

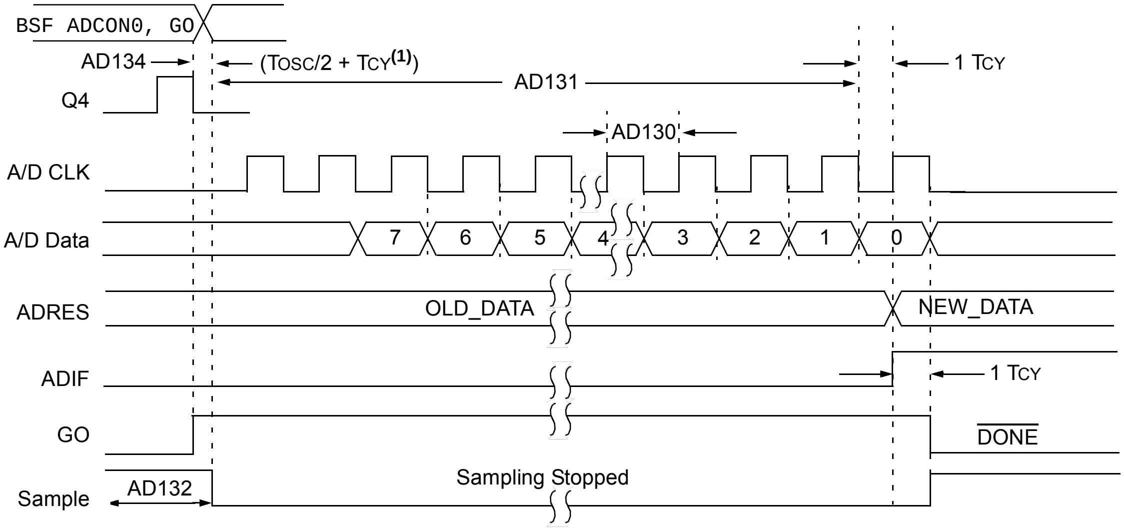
6: 8 MHz crystal oscillator with 4x PLL enabled.

FIGURE 30-12: PIC16(L)F1934/6/7 A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the `SLEEP` instruction to be executed.

FIGURE 30-13: PIC16(L)F1934/6/7 A/D CONVERSION TIMING (SLEEP MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the `SLEEP` instruction to be executed.

TABLE 30-16: I^{2}C™ BUS DATA REQUIREMENTS

Param. No.	Symbol	Characteristic		Min.	Max.	Units	Conditions
SP100*	T_{HIGH}	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			SSP module	1.5T_{CY}	—		
SP101*	T_{LOW}	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			SSP module	1.5T_{CY}	—		
SP102*	T_R	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	$20 + 0.1C_B$	300	ns	C_B is specified to be from 10-400 pF
SP103*	T_F	SDA and SCL fall time	100 kHz mode	—	250	ns	
			400 kHz mode	$20 + 0.1C_B$	250	ns	C_B is specified to be from 10-400 pF
SP106*	$T_{HD:DAT}$	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
SP107*	$T_{SU:DAT}$	Data input setup time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
SP109*	T_{AA}	Output valid from clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
SP110*	T_{BUF}	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
SP111	C_B	Bus capacitive loading		—	400	pF	

* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

2: A Fast mode (400 kHz) I^{2}C™ bus device can be used in a Standard mode (100 kHz) I^{2}C bus system, but the requirement $T_{SU:DAT} \geq 250$ ns must then be met. This will automatically be the case if the device does not stretch the low period of the SCL signal. If such a device does stretch the low period of the SCL signal, it must output the next data bit to the SDA line T_R max. + $T_{SU:DAT} = 1000 + 250 = 1250$ ns (according to the Standard mode I^{2}C bus specification), before the SCL line is released.

FIGURE 31-26: PIC16F1937 LP OSCILLATOR MODE, FOSC = 32 kHz

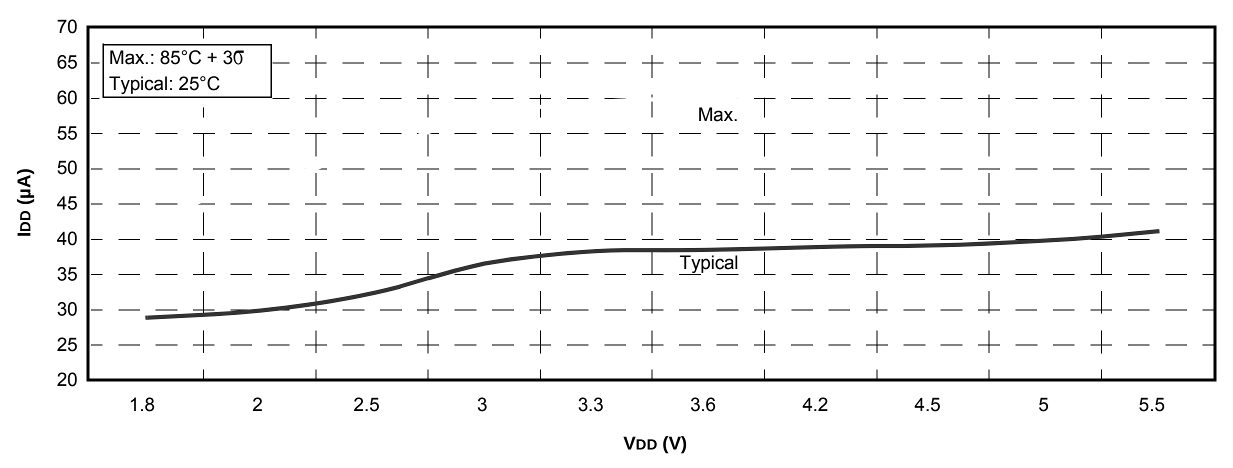


FIGURE 31-27: PIC16LF1937 HS OSCILLATOR MODE, FOSC = 32 MHz

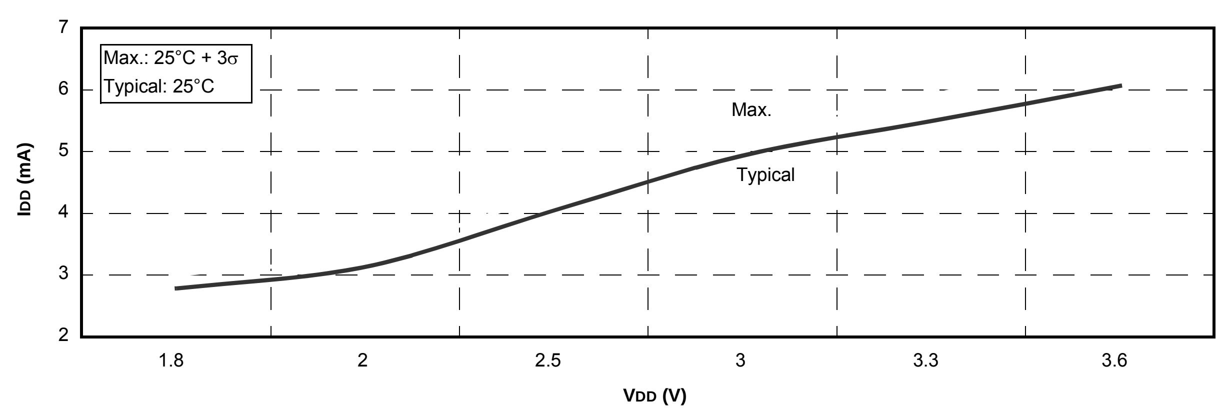


FIGURE 31-28: PIC16F1937 HS OSCILLATOR MODE, FOSC = 32 MHz

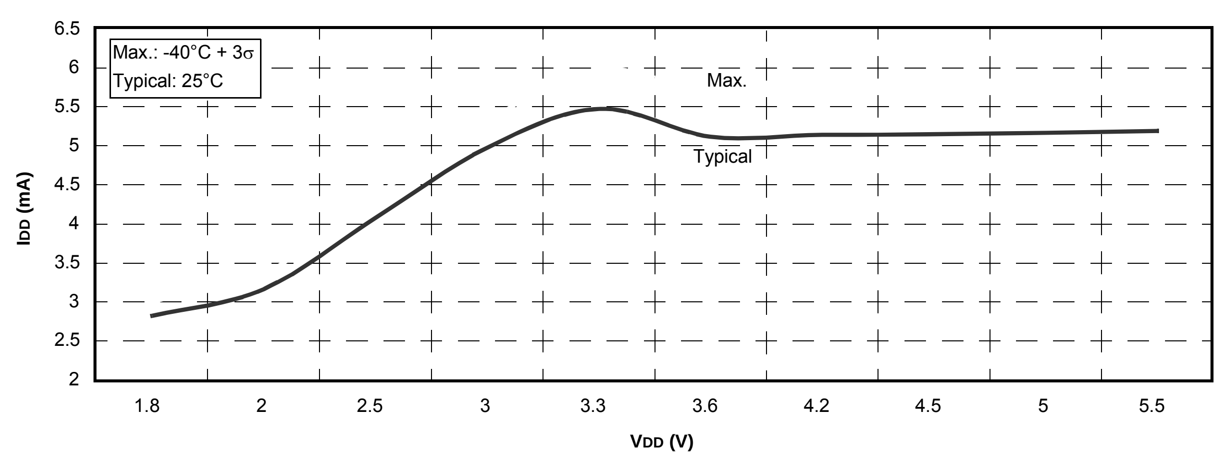


FIGURE 31-29: PIC16LF1937 EXTRC MODE, FOSC = 4 MHz

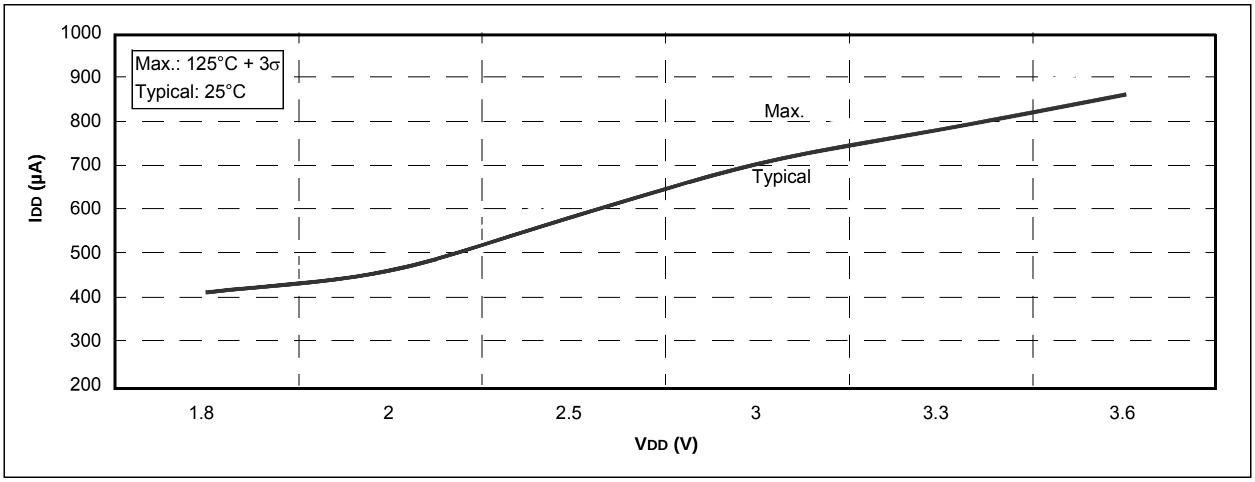


FIGURE 31-30: PIC16LF1937 XT OSCILLATOR, FOSC = 1 MHz

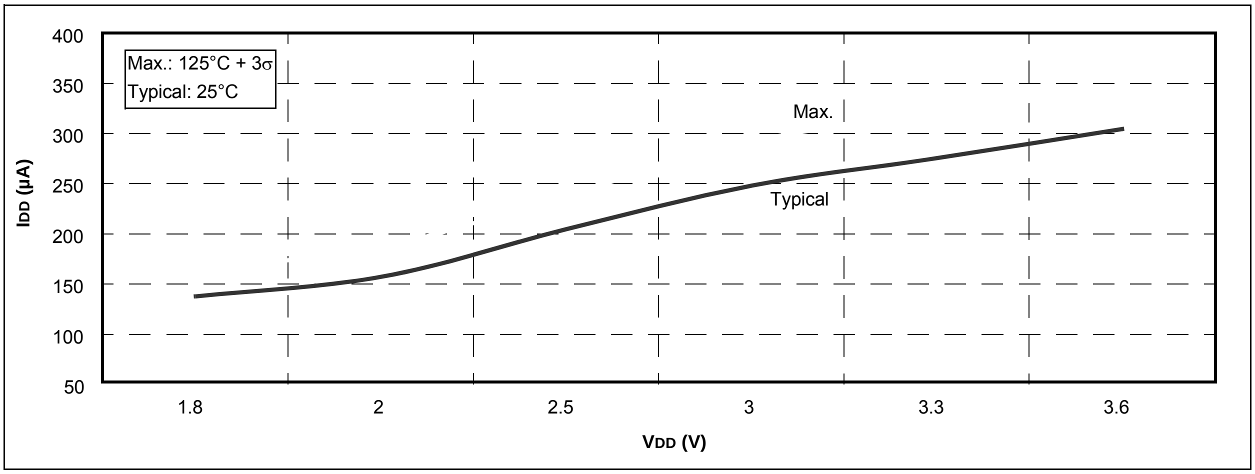


FIGURE 31-31: PIC16F1937 XT OSCILLATOR, FOSC = 1 MHz

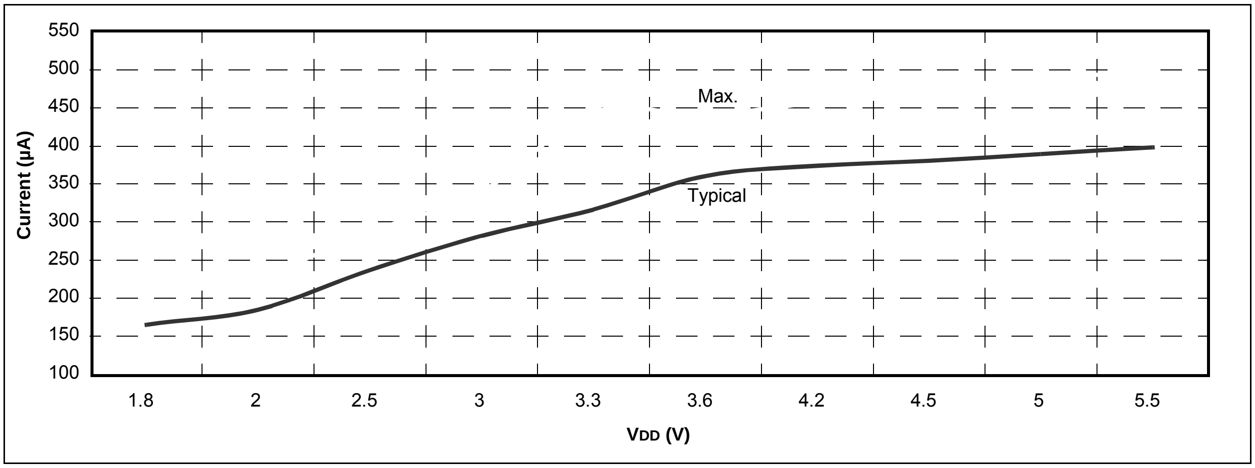


FIGURE 31-32: PIC16LF1937 XT OSCILLATOR, FOSC = 4 MHz

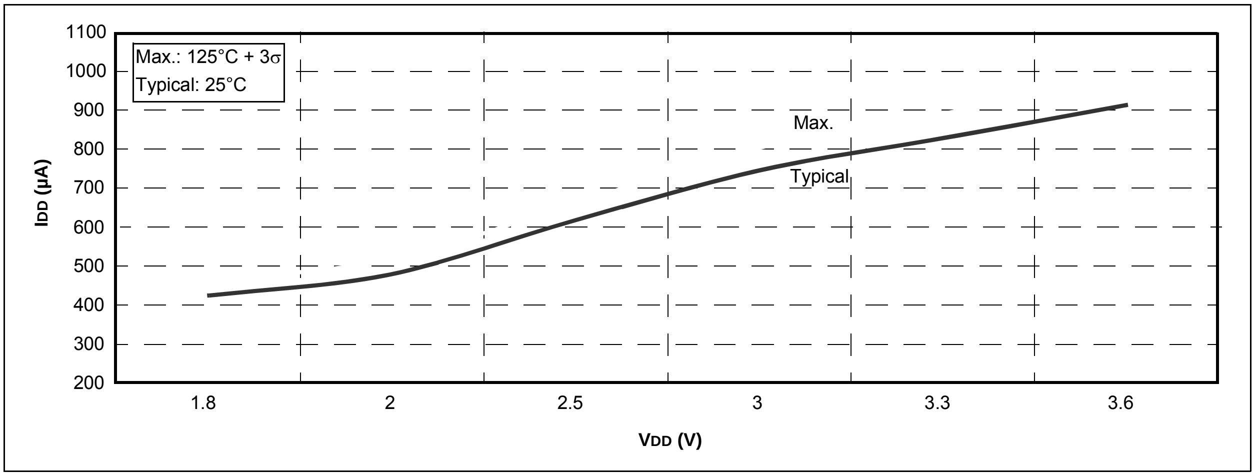


FIGURE 31-33: PIC16F1937 XT OSCILLATOR, FOSC = 4 MHz

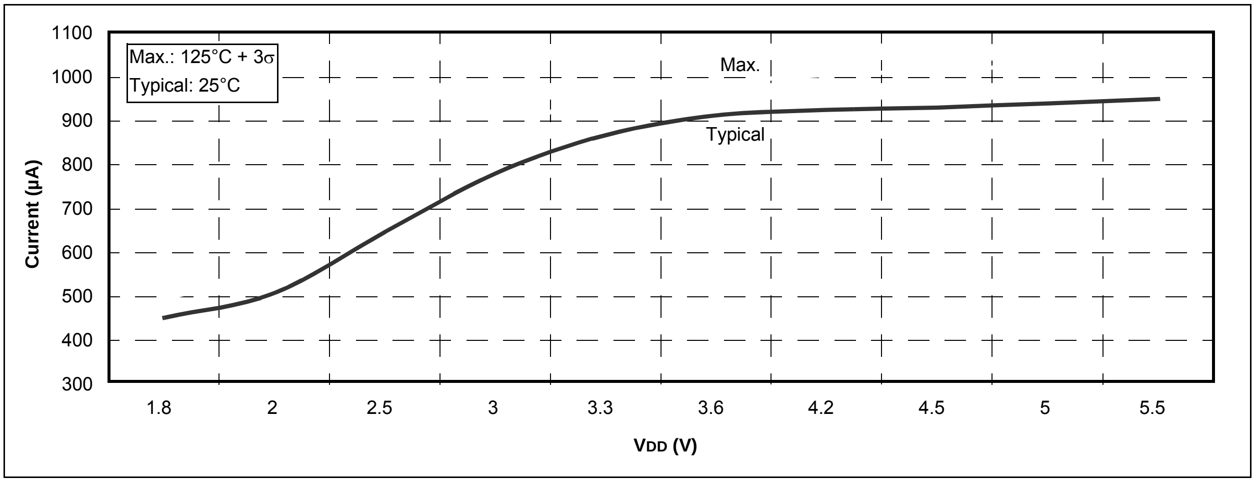
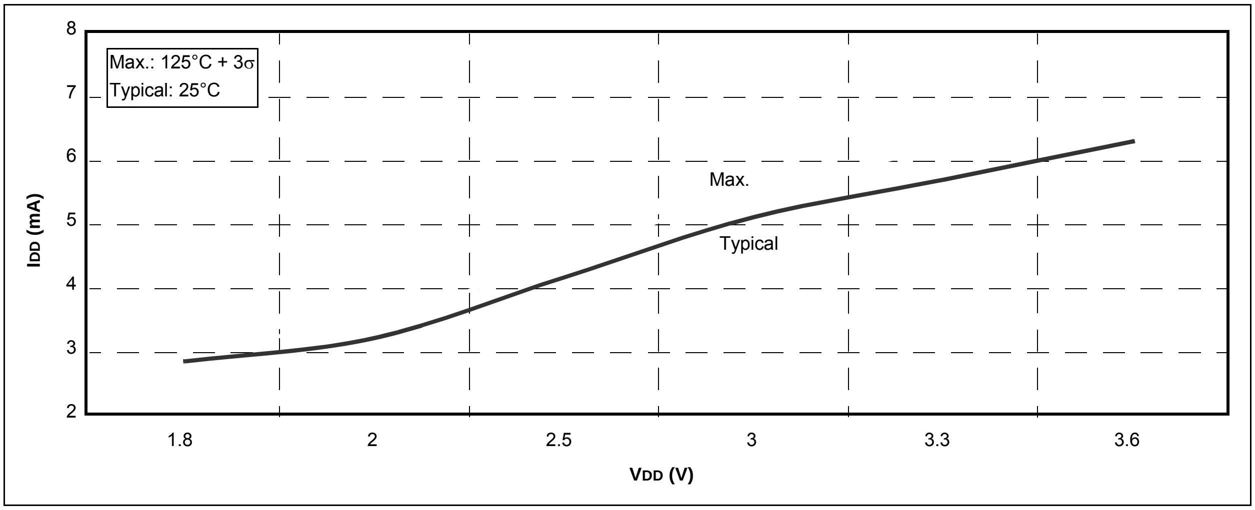
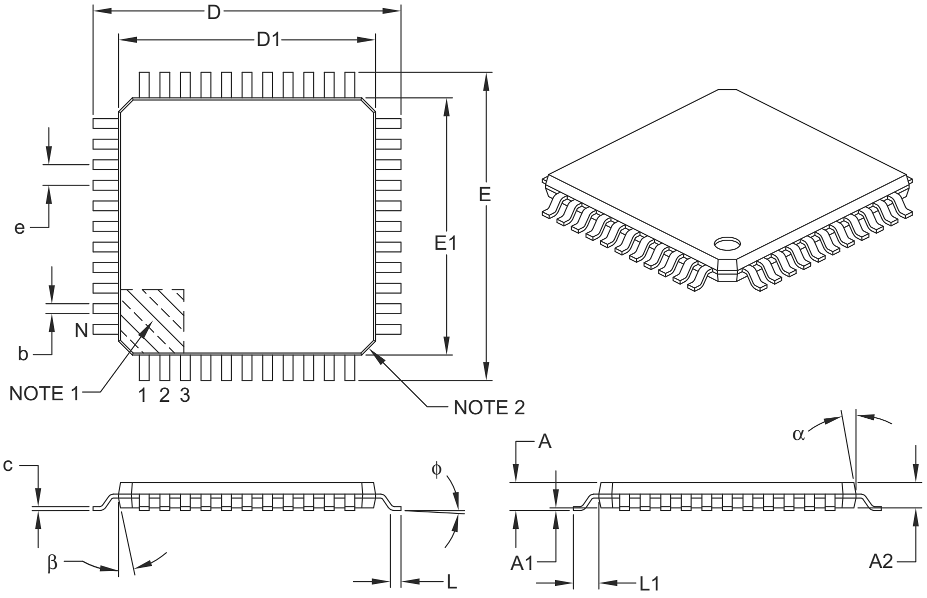


FIGURE 31-34: PIC16LF1937 EC OSCILLATOR, HIGH-POWER MODE, FOSC = 32 MHz



44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		Units	MILLIMETERS	
		Dimension Limits	MIN	NOM	MAX
Number of Leads	N	44		
Lead Pitch	e	0.80 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

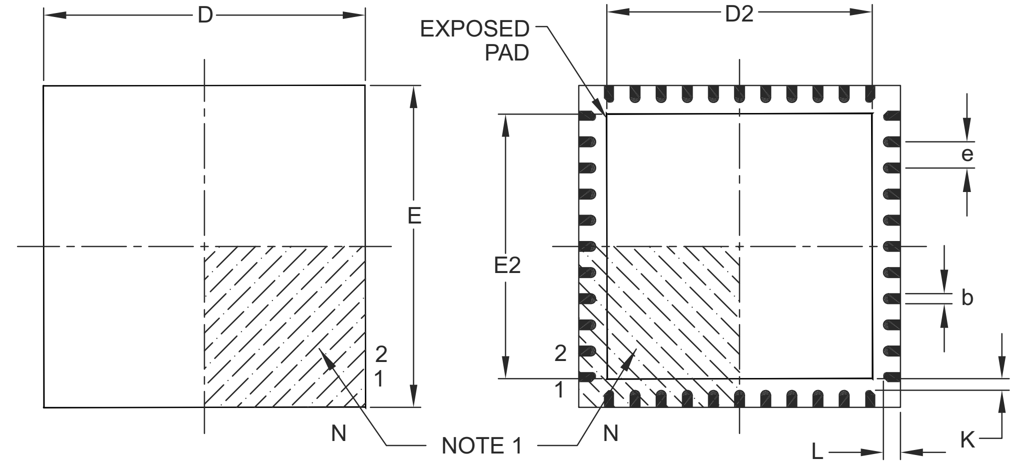
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

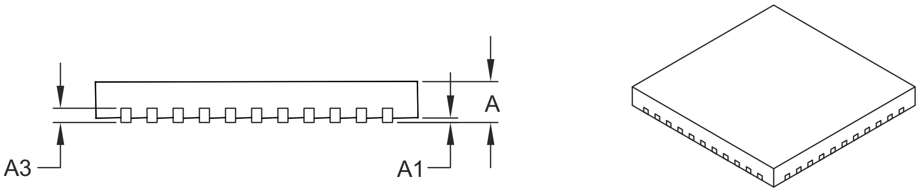
44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW

BOTTOM VIEW



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	44		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Width	E	8.00 BSC		
Exposed Pad Width	E2	6.30	6.45	6.80
Overall Length	D	8.00 BSC		
Exposed Pad Length	D2	6.30	6.45	6.80
Contact Width	b	0.25	0.30	0.38
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B

NOTES: